

# N-channel SiC power MOSFET

V <sub>DSS</sub>	1200V
R <sub>DS(on)</sub> (Typ.)	$80$ m $\Omega$
I <sub>D</sub>	31A
$P_D$	165W

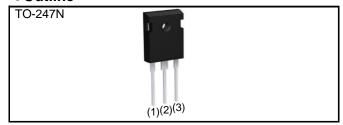
#### Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

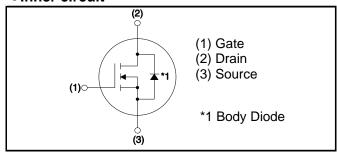
#### Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

#### Outline



#### ●Inner circuit



Packaging specifications

or working opcomoducing						
Packing	Packing	Tube				
	Reel size (mm)	-				
Typo	Tape width (mm)	-				
Type	Basic ordering unit (pcs)	30				
	Taping code	C11				
	Marking	SCT3080KL				

### ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	1200	V
Continuous drain current	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	31	А
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	22	А
Pulsed drain current	I <sub>D,pulse</sub> *2	77	А	
Gate - Source voltage		$V_{GSS}$	−4 to 22	V
Junction temperature	T <sub>j</sub>	175	°C	
Range of storage temperature	$T_{stg}$	-55 to +175	°C	

#### ●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R <sub>thJC</sub>	-	0.70	0.91	°C/W

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions		Values			Unit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	1200	-	1	V
		$V_{DS} = 1200V, V_{GS} = 0V$				
Zero gate voltage drain current	I <sub>DSS</sub>	T <sub>j</sub> = 25°C	-	1	10	μΑ
		T <sub>j</sub> = 150°C	-	2	-	
Gate - Source leakage current	I <sub>GSS+</sub>	$V_{GS} = +22V, V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current	$I_{GSS-}$	$V_{GS} = -4V$ , $V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V$ , $I_D = 5mA$	2.7	-	5.6	V
		$V_{GS} = 18V, I_D = 10A$				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *3	T <sub>j</sub> = 25°C	-	80	104	mΩ
2 2		T <sub>j</sub> = 125°C	-	120	-	
Gate input resistance	$R_{G}$	f = 1MHz, open drain	-	12	-	Ω

### ●Electrical characteristics (T<sub>a</sub> = 25°C)

Doromotor	Symbol Conditions -		Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Transconductance	g <sub>fs</sub> *3	$V_{DS} = 10V, I_D = 10A$	-	4.4	-	S
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	785	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 800V	-	75	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	35	-	
Effective output capacitance, energy related	C <sub>o(er)</sub>	$V_{GS} = 0V$ $V_{DS} = 0V$ to 600V	-	74	-	pF
Turn - on delay time	t <sub>d(on)</sub> *3	$V_{DD} = 400V, I_D = 10A$	-	15	-	
Rise time	t <sub>r</sub> *3	V <sub>GS</sub> = 18V/0V	-	22	-	no
Turn - off delay time	t <sub>d(off)</sub> *3	$R_L = 40\Omega$	-	29	-	ns
Fall time	t <sub>f</sub> *3	$R_G = 0\Omega$	-	24	-	
Turn - on switching loss	E <sub>on</sub> *3	$V_{DD} = 600V, I_{D} = 10A$ $V_{GS} = 18V/0V$	-	132	-	1
Turn - off switching loss	E <sub>off</sub> *3	$R_G = 0\Omega L=750\mu H$ * $E_{on}$ includes diode reverse recovery	-	18	-	μJ

### •Gate Charge characteristics ( $T_a = 25$ °C)

Parameter	Symbol Conditions -	Conditions	Values			Unit
		Min.	Тур.	Max.	Onit	
Total gate charge	$Q_g^{*3}$	V <sub>DD</sub> = 600V	-	60	ı	
Gate - Source charge	Q <sub>gs</sub> *3	I <sub>D</sub> = 10A	-	15	-	nC
Gate - Drain charge	Q <sub>gd</sub> *3	V <sub>GS</sub> = 18V	-	25	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} = 600V, I_D = 10A$	-	9.6	ı	V

<sup>\*1</sup> Limited only by maximum temperature allowed.

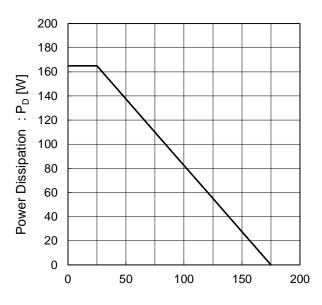
<sup>\*2</sup> PW  $\leq$  10  $\mu s,$  Duty cycle  $\leq$  1%

<sup>\*3</sup> Pulsed

## ullet Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

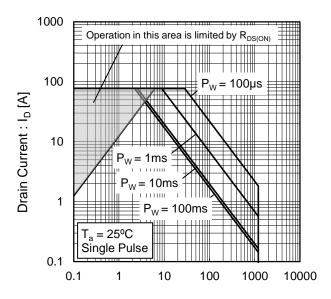
Parameter	Symbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Inverse diode continuous, forward current	l <sub>S</sub> *1	-T <sub>c</sub> = 25°C	-	1	31	А
Inverse diode direct current, pulsed	I <sub>SM</sub> *2		-	-	77	А
Forward voltage	V <sub>SD</sub> *3	$V_{GS} = 0V, I_{S} = 10A$	-	3.2	-	V
Reverse recovery time	t <sub>rr</sub> *3	I <sub>F</sub> =10A, V <sub>R</sub> = 600V di/dt = 1100A/μs	-	17	ı	ns
Reverse recovery charge	Q <sub>rr</sub> *3		-	50	-	nC
Peak reverse recovery current	I <sub>rrm</sub> *3		-	6	-	Α

Fig.1 Power Dissipation Derating Curve



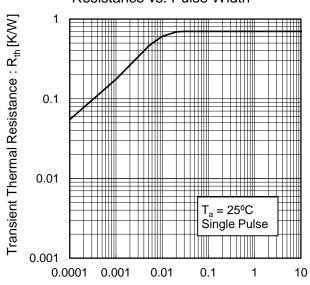
Junction Temperature :  $T_i$  [°C]

Fig.2 Maximum Safe Operating Area



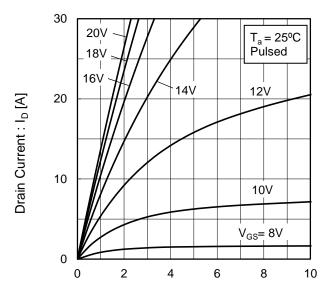
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



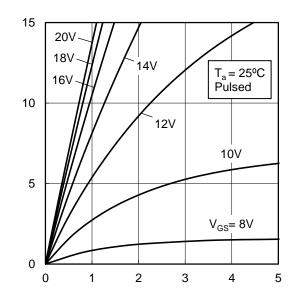
Pulse Width :  $P_W$  [s]

Fig.4 Typical Output Characteristics(I)



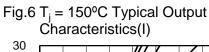
Drain - Source Voltage :  $V_{DS}[V]$ 

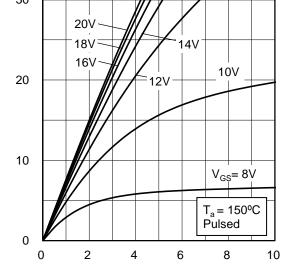
Fig.5 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

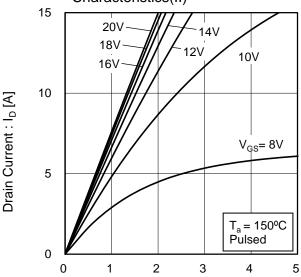
Drain - Source Voltage : V<sub>DS</sub> [V]





Drain - Source Voltage :  $V_{DS}[V]$ 

Fig.7  $T_j = 150^{\circ}$ C Typical Output Characteristics(II)



Drain - Source Voltage : V<sub>DS</sub> [V]

Drain Current : I<sub>D</sub> [A]

Fig.8 Typical Transfer Characteristics (I)

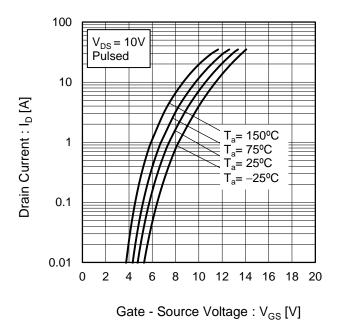
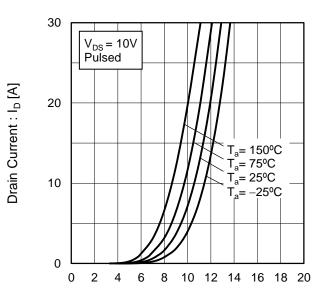


Fig.9 Typical Transfer Characteristics (II)



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.10 Gate Threshold Voltage

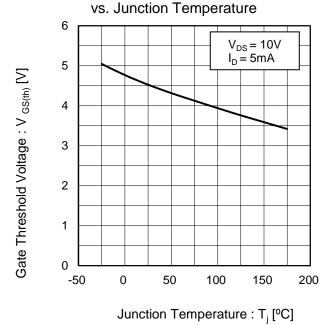
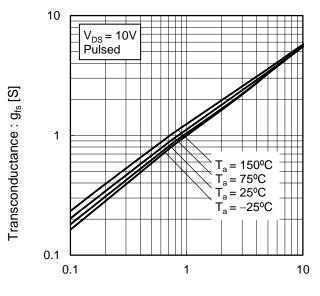


Fig.11 Transconductance vs. Drain Current



Drain Current : I<sub>D</sub> [A]

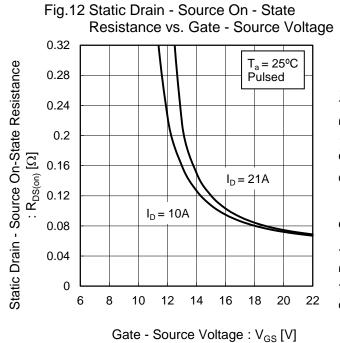
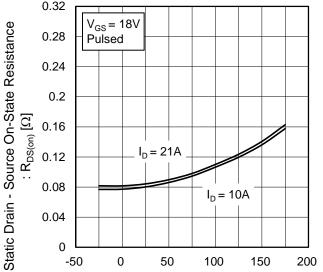
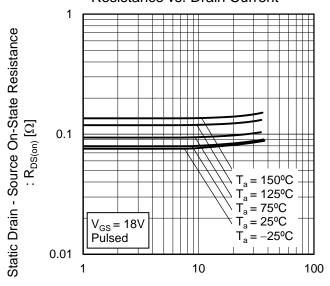


Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature



Junction Temperature : T<sub>i</sub> [°C]

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current

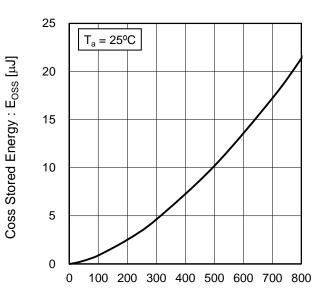


Drain Current: I<sub>D</sub> [A]

Fig.15 Typical Capacitance vs. Drain - Source Voltage 10000 1000 Capacitance: C [pF] 100 10 = 25°C 1MHz  $G_S = 0V$ 1 0.1 10 100 1000

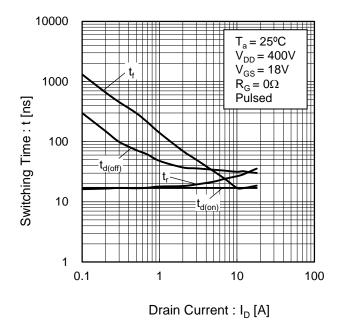
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.16 Coss Stored Energy



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.17 Switching Characteristics



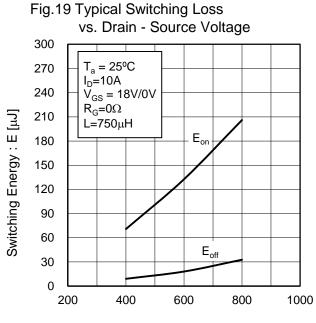
15 10

3ate - Source Voltage : V<sub>GS</sub> [V]

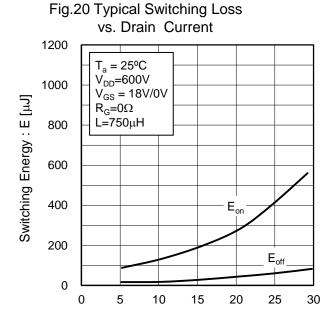
20  $T_a = 25^{\circ}C$  $V_{DD} = 600V$   $I_{D} = 10A$ Pulsed 5 0 0 10 20 30 40 50 60 70

Fig.18 Dynamic Input Characteristics

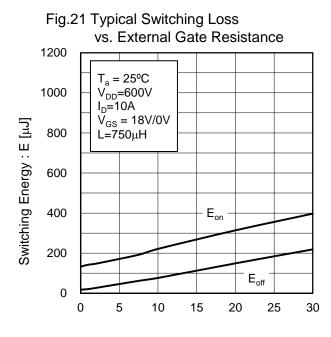
Total Gate Charge : Q<sub>g</sub> [nC]



Drain - Source Voltage : V<sub>DS</sub> [V]

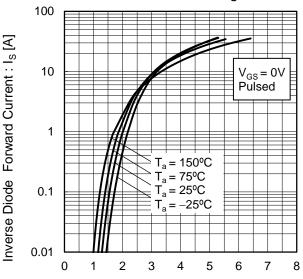


Drain Current : I<sub>D</sub> [A]



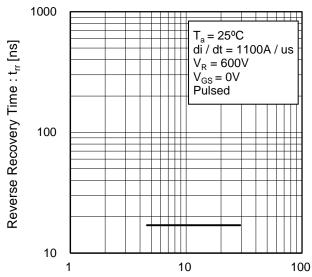
External Gate Resistance :  $R_G[\Omega]$ 

Fig.22 Inverse Diode Forward Current vs. Source - Drain Voltage



Source - Drain Voltage : V<sub>SD</sub> [V]

Fig.23 Reverse Recovery Time vs.Inverse Diode Forward Current



Inverse Diode Forward Current : I<sub>S</sub> [A]

#### ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

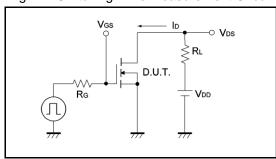


Fig.2-1 Gate Charge Measurement Circuit

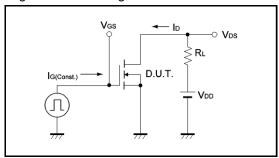


Fig.3-1 Switching Energy Measurement Circuit

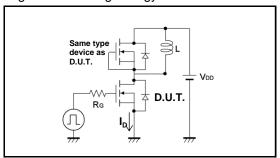


Fig.4-1 Reverse Recovery Time Measurement Circuit Fig.4-2 Reverse Recovery Waveform

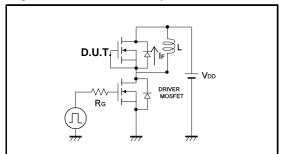


Fig.1-2 Switching Waveforms

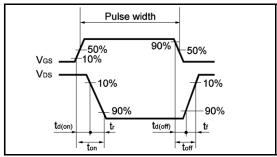


Fig.2-2 Gate Charge Waveform

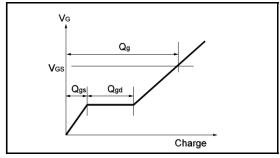
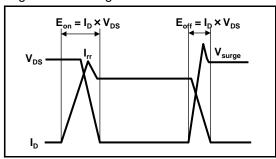
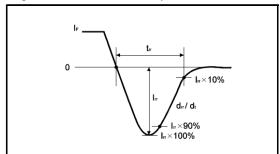


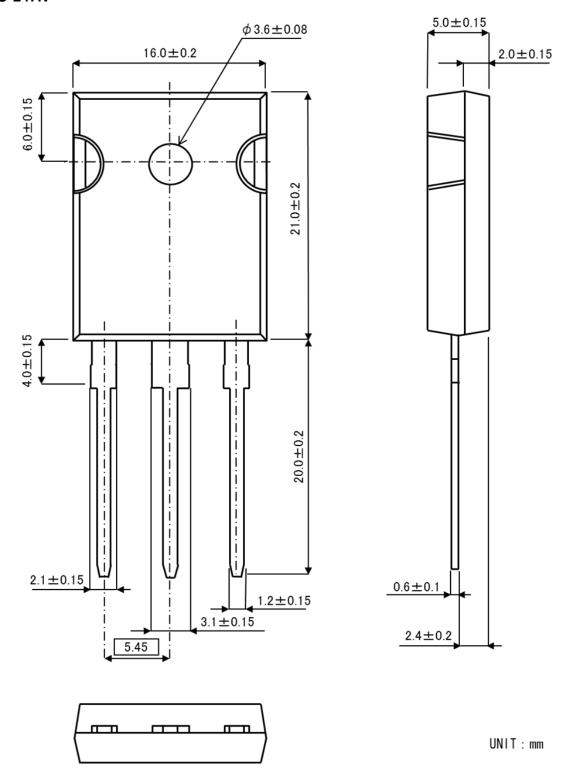
Fig.3-2 Switching Waveforms





#### Dimensions

#### **TO-247N**



#### Notes

- 1) The information contained herein is subject to change without notice.
- Before you use our Products, please contact our sales representative and verify the latest specifications:
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.
- 4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.
- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
- 6) The Products specified in this document are not designed to be radiation tolerant.
- 7) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative: transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.
- 8) Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.
- 9) ROHM shall have no responsibility for any damages or injury arising from non-compliance with the recommended usage conditions and specifications contained herein.
- 10) ROHM has used reasonable care to ensur the accuracy of the information contained in this document. However, ROHM does not warrants that such information is error-free, and ROHM shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
- 11) Please use the Products in accordance with any applicable environmental laws and regulations, such as the RoHS Directive. For more details, including RoHS compatibility, please contact a ROHM sales office. ROHM shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
- 12) When providing our Products and technologies contained in this document to other countries, you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act.
- 13) This document, in part or in whole, may not be reprinted or reproduced without prior consent of ROHM.



Thank you for your accessing to ROHM product informations.

More detail product informations and catalogs are available, please contact us.

### ROHM Customer Support System

http://www.rohm.com/contact/



# SCT3080KL - Web Page

Part Number	SCT3080KL
Package	TO-247N
Unit Quantity	450
Minimum Package Quantity	30
Packing Type	Tube
Constitution Materials List	inquiry
RoHS	Yes